



Material Content Data Sheet



Sales Product Name		TLE7273-2E V50		Issued		25. September 2017		
MA#		MA000970210						
Package		PG-SSOP-14-2		Weight*		83.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.362	2.83	2.83	28334	28334
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8266	
wire	non noble metal	copper	7440-50-8	27.978	33.56	34.44	335633	344415
	noble metal	gold	7440-57-5	0.171	0.20	0.20	2046	2046
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1176
plastics		epoxy resin	-	4.510	5.41		54110	
	inorganic material	silicondioxide	60676-86-0	44.418	53.29	58.82	532862	588148
leadfinish	non noble metal	tin	7440-31-5	0.988	1.19	1.19	11856	11856
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9209	9209
glue	plastics	epoxy resin	-	0.333	0.40		3998	
	noble metal	silver	7440-22-4	1.000	1.20	1.60	11994	15992
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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